

HZL6.8Z4

Silicon Planar Zener Diode for Surge Absorb

REJ03G0410-0100

Rev.1.00

Oct 01, 2004

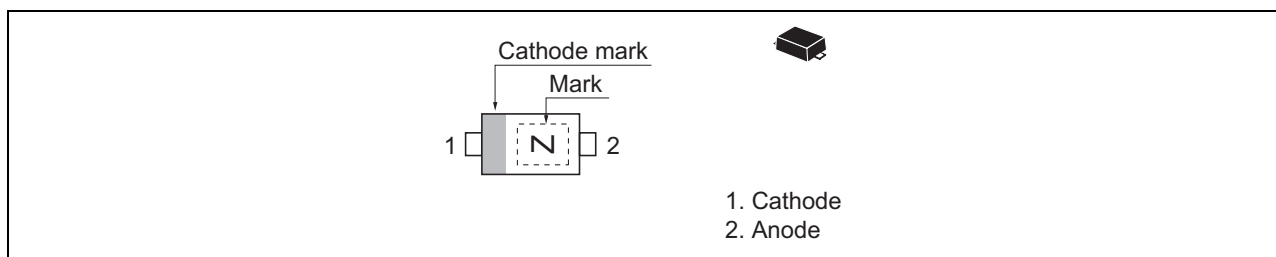
Features

- Low capacitance ($C = 4.0 \text{ pF max}$) and can protect ESD of signal line.
- Extremely small Flat Package (EFP) is suitable for surface mount design.

Ordering Information

Type No.	Laser Mark	Package Code
HZL6.8Z4	Z	EFP

Pin Arrangement



Absolute Maximum Ratings

(Ta = 25°C)

Item	Symbol	Value	Unit
Power dissipation	Pd *	100	mW
Junction temperature	Tj	150	°C
Storage temperature	Tstg	-55 to +150	°C

Note: See Fig.2.

Electrical Characteristics

(Ta = 25°C)

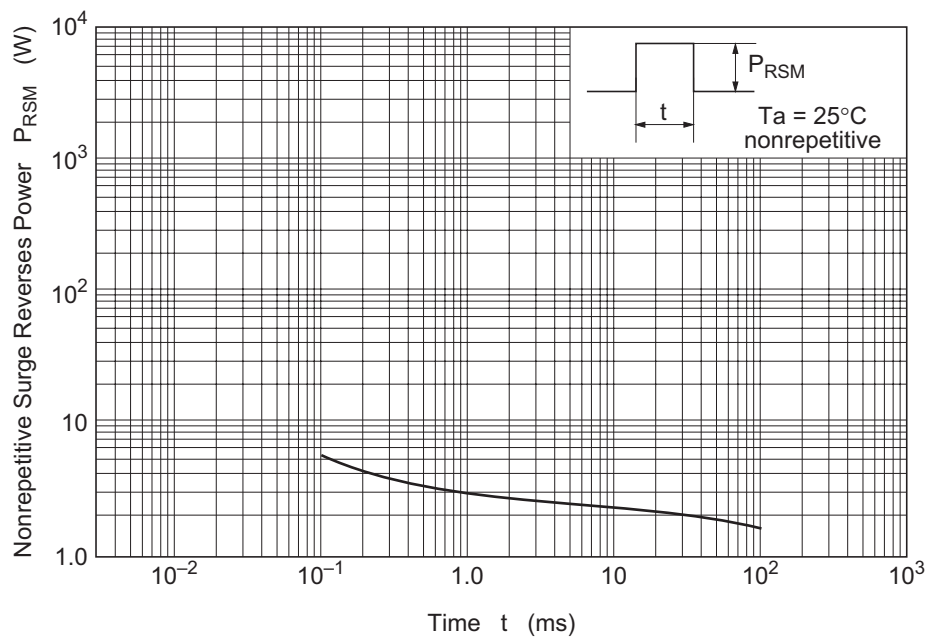
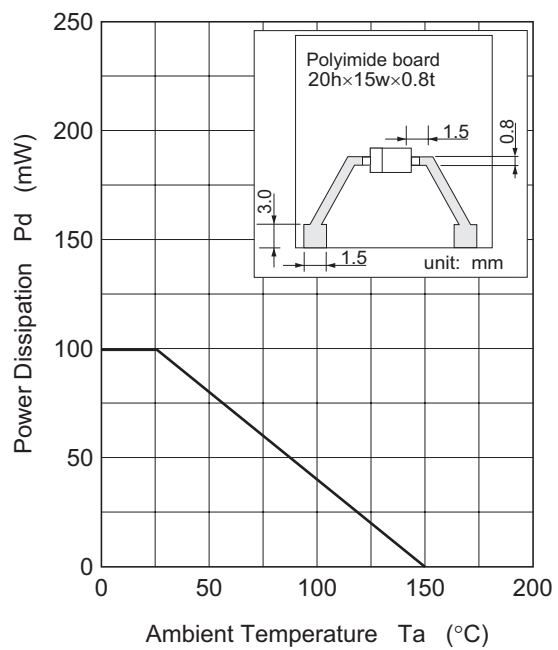
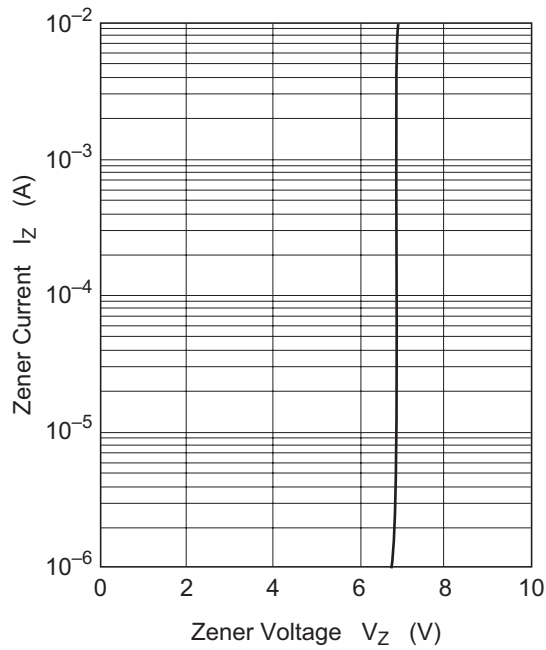
Item	Symbol	Min	Typ	Max	Unit	Test Condition
Zener voltage	V _Z	6.47	—	7.00	V	I _Z = 5 mA, 40 ms pulse
Reverse current	I _R	—	—	2	μA	V _R = 3.5 V
Capacitance	C	—	—	4.0	pF	V _R = 0 V, f = 1 MHz
Dynamic resistance	r _d	—	—	30	Ω	I _Z = 5 mA
ESD-Capability * ¹	—	8	—	—	kV	C = 150 pF, R = 330 Ω, Both Forward and reverse direction 10 pulse

Notes: 1. Failure criterion ; I_R > 2 μA at V_R = 3.5 V.

2. Please do not use the soldering iron due to avoid high stress to the EFP package.

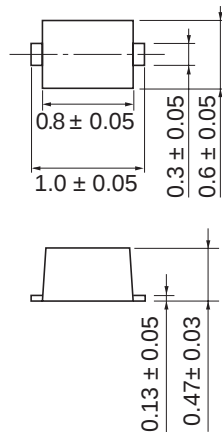
3. The material of lead is exposed for cutting plane. There for, soldering nature of lead tip part is considered as unquestioned. Please kindly consider soldering nature.

Main Characteristic



Package Dimensions

As of January, 2003
Unit: mm



Package Code	EFP
JEDEC	—
JEITA	—
Mass (reference value)	0.0007 g

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